CoolFlex

CoolFlex is an innovative application of existing flexible circuit technology to improve DRAM module electrical, mechanical and thermal performance. Flex circuits have been employed in automotive and military applications for decades, making CoolFlex a natural extension of technology.

CoolFlex is a DRAM module technology that utilizes a double-sided, multi-layer flexible circuit with an integrated edge connector folded around a rigid core, typically made of aluminum.

Since the effective Printed Circuit Board (PCB) area is doubled by placing DRAM on the inside and outside surfaces, increasing the component density without sacrificing speed. Now, high-density memory modules can be realized without costly DRAM stacking for all DDR3 RDIMMs and VLP (Very Low Profile) DIMMs.

Features & Specifications

Advantages

- Double Surface Area for High Density
- Thin Profile a More airflow, tighter DIMM spacing
- Thermally Enhanced Core
- Improved Electrical Performance, Better Margins
- High Durability and Reliability
- JEDEC®/RoHS Compliant
- Cost Effective

Applications

- Network routers
- Telecom switching equipment
- Storage server applications
- 1U servers

Ordering Information

<table>
<thead>
<tr>
<th>DDR3 Flash Back RDIMM</th>
<th>Density</th>
<th>Height (in)</th>
<th>Module Config.</th>
<th>Voltage</th>
<th>Speed</th>
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<tbody>
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<td>32GB</td>
<td>0.76</td>
<td>2G x4</td>
<td>1.5V</td>
<td>1600 MHz</td>
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